

CW9253-125 Data sheet

Four-channel 14 Bit 125MSPS ADC

1.0 overview

The CW9253-125 is a 4-channel, 14-bit, 125MSPS analog-to-digital converter (ADC) with built-in sample and hold circuitry, specifically designed for low cost, low power consumption, small size and ease of use. The product has a conversion rate of up to 125MSPS, excellent dynamic performance and low power consumption, and is suitable for small package applications.

The CW9253-125 is powered by a 1.8 V single power supply and an LVPECL/CMOS/LVDS compatible sample rate clock signal to maximize its performance. For most applications, no external reference power supply or driver device is required.

To obtain the appropriate LVDS serial data rate, the CW9253-125 automatically multiplies the sample rate clock. It provides a data clock output (DCO) for capturing data at the output, and a frame clock output (FCO) for sending a new output byte signal. It also supports each channel to enter the power-saving state independently; Typical power consumption less than 2.2 mW when all channels are closed

2.0 Applications

- Medical imaging and non-invasive ultrasound testing
- High-speed imaging
- Radio receiver
- Test equipment

3.0 peculiarity

- 1.8 V Power Supply
- Low power consumption: per channel 170mW @ 125MSPS
- Signal-to-noise ratio(SNR): 76.5 dBFS @ 70MHz
- Differential nonlinearity(DNL): ± 0.7 LSB (Typical value)
- Integral nonlinearity(INL): ± 3.5 LSB (Typical value)
- Low power serial LVDS
- 2V_{P-P} Input voltage range
- QFN-48 Encapsulation 7 mm × 7 mm

4.0 Performance indicators

- Full power bandwidth: 650 MHz
- Static performance: DNL-1.0/+1.0 LSB, INL-5.0/+5.0 LSB
- Dynamic performance ($f_s = 125\text{MSps}$, input signal power-1 dBFS)
 - $f_{in} = 9.7\text{ MHz}$
ENOB = 11.7 Bit, SNDR = 72 dBFS, SNR = 72.5 dBFS
 - $f_{in} = 70\text{ MHz}$
ENOB = 11.2 Bit, SNDR = 69 dBFS, SNR = 69.5 dBFS
 - $f_{in} = 128\text{ MHz}$
ENOB = 10.5 Bit, SNDR = 64.7 dBFS, SNR = 65.3 dBFS
 - $f_{in} = 200\text{ MHz}$
ENOB = 10 Bit, SNDR = 61.9 dBFS, SNR = 62.5 dBFS

5.0 Simplified block diagram

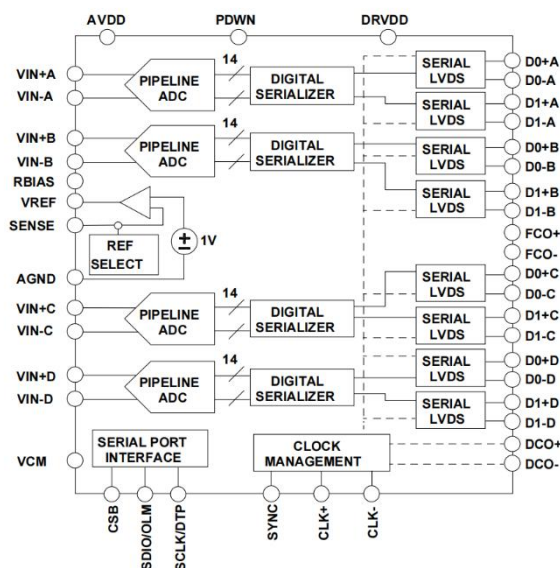


Figure 5.1 CW9253-125 System block diagram

6.0 Typical performance

TABLE6-1 Conditions of use of chips

parameter	Symbols	annotation	Numerical value	Units
Power supply voltage	V _A	Analog circuit power supply	1.8	V
	V _{DR}	Output drive circuit power supply	1.8	V
Power-on sequence		No power-on sequence requirement		
Ground	GND _A	Analog circuit ground	0	V
	GND _{DR}	Output drive circuit ground	0	V
Differential input analog signal amplitude ⁽¹⁾	V _{INIP} – V _{ININ} V _{INQP} – V _{INQN}	Differential amplitude of input signal	2000	mVpp
Logic input high	V _{IH}		V _A	V
Logic input low	V _{IL}		GND	
Clock differential input signal swing	V _{CLKP} – V _{CLKN}		200 ≤ V _{CLKP} – V _{CLKN} ≤ 3600	mVpp
Clock frequency	f _{CLK}		f _{CLK} ≤ 1000	MHz
Conversion rate	f _s		20-125	MSPS
Operating temperature range	T _A		-55 ≤ T _A ≤ 125	°C

NOTE:

(1) Measurement conditions are input frequency, full-scale sine wave, load per output bit of approx5pF。

TABLE6-2 Electrical characteristics of power supply, inputs and outputs

Unless otherwise indicated,AVDD=1.8 V, DRVDD=1.8 V, -1.0 dBFS The full-scale differential input is2.0 V p-p; VREF=1.0V, DCS OFF.

parameter	Symbols	Minimum	Typical value	Maximum	Units
Resolution			14		Bit
Supply voltage:					
Analog circuit power supply	V _A	1.7	1.8	1.9	V
Output drive circuit power supply	V _{DR}	1.7	1.8	1.9	V
Supply Current:					
Analog circuit power supply	I _A		310		mA
Output drive circuit power supply	I _{DR}		70		mA
Analog input:					
Input differential analog signal amplitude	V _{INIP} – V _{ININ}	0.3	2	V _A	Vpp
Common mode voltage	V _{CM}		0.9		V
Differential input resistance	R _{IN}		2.6		kΩ
Clock input:	Differential sine wave				
Logic compatibility	CMOS/LVDS/LVPECL				
Input clock rate	f _{MCLK}	20		1000	MHz
Input differential swing	V _{CLKP} – V _{CLKN}	200	900	3600	mVpp
Input common mode voltage	V _{CM} _ CLK		0.9		V
Clock differential input resistance	R _{CLK}		15		kΩ
Internal reference voltage:					
Output voltage (1.0 V mode)	V _{REF}		1		V
Input resistance			7.5		kΩ
Power consumption:					
DC input power consumption			620		mW
Sine wave input power consumption			660		mW
Shutdown power consumption	PD		2.2		mW

TABLE6-3 Static characteristics

parameter	Symbols	Minimum	Typical value	Maximum	Units
Differential nonlinearity	DNL	-1.0	0.75	1.0	LSB
Integral nonlinearity	INL	-5.0	3	5.0	LSB

TABLE6-4 Dynamic characteristic(Reference)

Unless otherwise indicated, AVDD=1.8 V, DRVDD=1.8 V, -1.0 dBFS The full-scale differential input is 2.0 V p-p; VREF=1.0 V, DCS OFF.

parameter	Symbols	Minimum	Typical value	Maximum	Units
$f_s = 125\text{MSPS}$, $V_{in} = -1\text{ dBFS}$					
Significant digits					
$f_{in} = 9.7\text{ MHz}$ (25°C)	ENOB	10.8	11.7		bit
$f_{in} = 15\text{ MHz}$ (25°C)			11.65		bit
$f_{in} = 70\text{ MHz}$ (Full temperature)					bit
$f_{in} = 128\text{ MHz}$ (25°C)			10.51		bit
$f_{in} = 200\text{ MHz}$ (25°C)			10.0		bit
Signal-to-noise ratio					
$f_{in} = 9.7\text{ MHz}$ (25°C)	SNR	67.8	72.5		dBFS
$f_{in} = 15\text{ MHz}$ (25°C)			72.3		dBFS
$f_{in} = 70\text{ MHz}$ (Full temperature)					dBFS
$f_{in} = 128\text{ MHz}$ (25°C)			65.8		dBFS
$f_{in} = 200\text{ MHz}$ (25°C)			62.5		dBFS
Signal ratio					
$f_{in} = 9.7\text{ MHz}$ (25°C)	SINAD	67.2	72.1		dBFS
$f_{in} = 15\text{ MHz}$ (25°C)			71.9		dBFS
$f_{in} = 70\text{ MHz}$ (Full temperature)					dBFS
$f_{in} = 128\text{ MHz}$ (25°C)			65		dBFS
$f_{in} = 200\text{ MHz}$ (25°C)			62.1		dBFS
Spur-free dynamic range					
$f_{in} = 9.7\text{ MHz}$ (25°C)	SFDR	79.3	88.5		dBc
$f_{in} = 15\text{ MHz}$ (25°C)			85.3		dBc
$f_{in} = 70\text{ MHz}$ (Full temperature)					dBc
$f_{in} = 128\text{ MHz}$ (25°C)			77.5		dBc
$f_{in} = 200\text{ MHz}$ (25°C)			71.4		dBc
Second harmonic					
$f_{in} = 9.7\text{ MHz}$ (25°C)	2nd Harm	80	97		dBc
$f_{in} = 15\text{ MHz}$ (25°C)			93		dBc
$f_{in} = 70\text{ MHz}$ (Full temperature)					dBc
$f_{in} = 128\text{ MHz}$ (25°C)			86		dBc
$f_{in} = 200\text{ MHz}$ (25°C)			80		dBc
Crosstalk (Full temperature)			90		dB
Analog input bandwidth (25°C)			650		MHz

Note: Measurement conditions of crosstalk: one channel input parameter is -1dBFS、70MHz Signal and no input signal on adjacent channels.

7.0 Pin configuration and function description

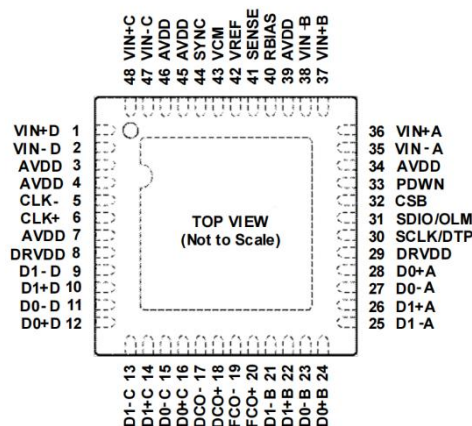


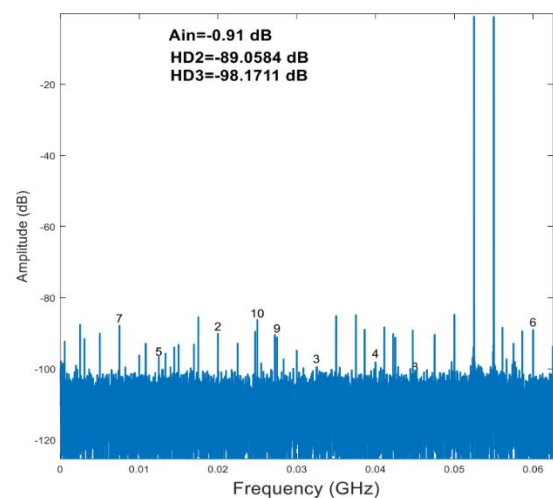
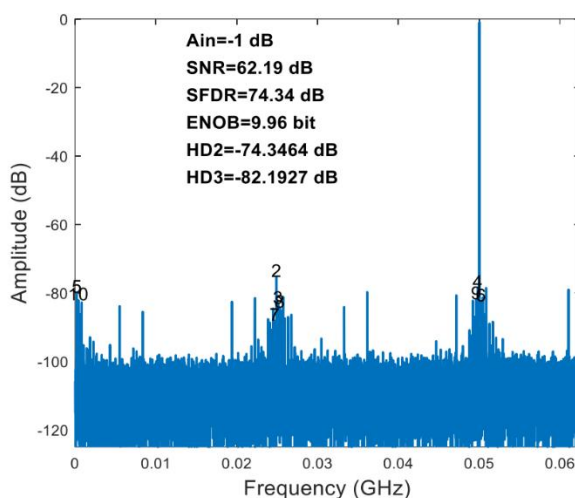
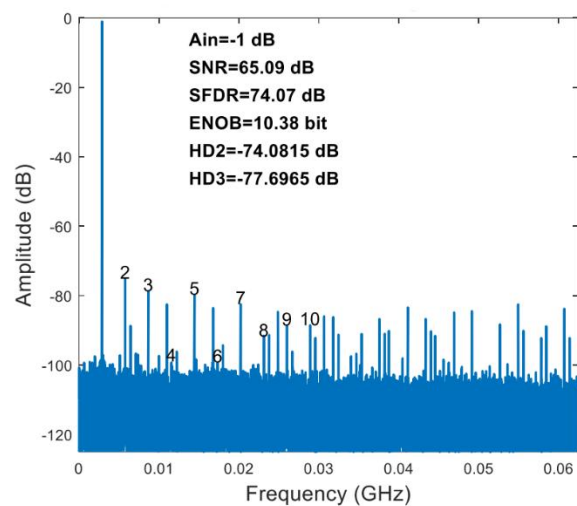
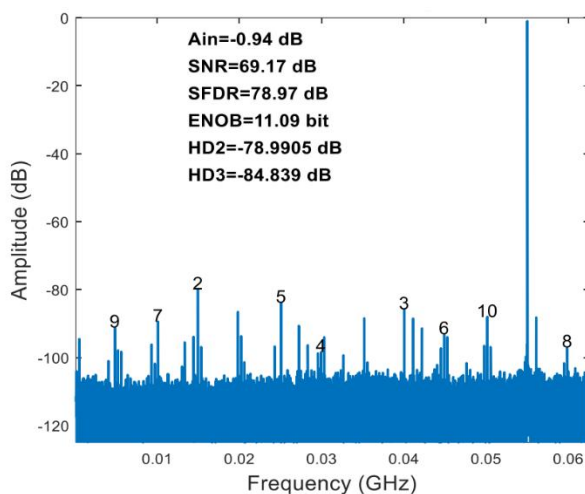
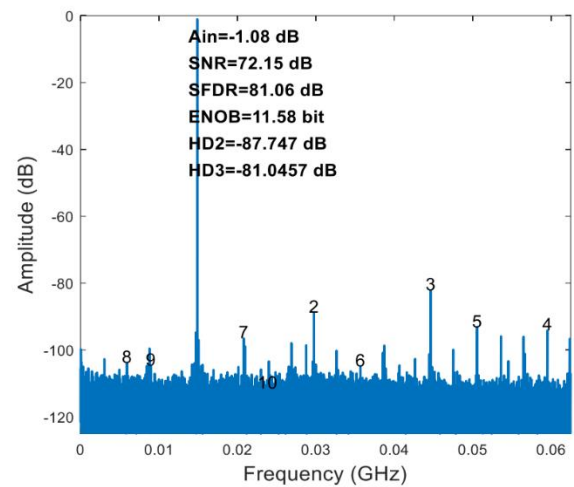
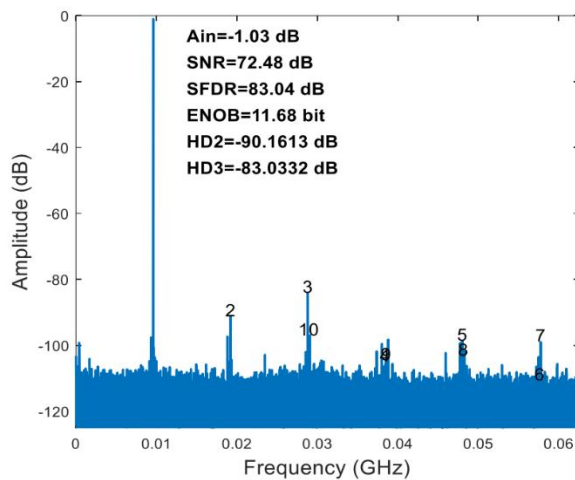
Figure7.1 CW9253-125 Pin arrangement (Top View)

TABLE7-1 Pin Function Description

Balloon serial number	Symbols	functionality
0	AGND, Exposed Pad	Analog ground with exposed pads. The bottom pad of the package provides analog ground for the chip. This exposed pad must be grounded for proper operation.
1	VIN + D	ChannelDAnalog input+
2	VIN - D	ChannelDAnalog input-
3, 4, 7, 34,39, 45, 46	AVDD	Analog power supply,1.8 V
5, 6	CLK -, CLK +	Differential clock input
8, 29	DRVDD	A digital output drive voltage source,1.8 V
9, 10	D 1 - D, D1 + D	ChannelDDigital Output
11, 12	D0 - D, D0 + D	ChannelDDigital Output
13, 14	D 1 - C, D1 + C	ChannelCDigital Output
15, 16	D 0 - C, D0 + C	ChannelCDigital Output
17, 18	DCO -, DCO +	Data clock output
19, 20	FCO -, FCO +	Frame clock output
21, 22	D 1 - B, D1 + B	ChannelBDigital Output
23, 24	D0 - B, D0 + B	ChannelBDigital Output
25, 26	D 1 - A, D1 + A	ChannelADigital Output
27, 28	D 0 - A, D0 + A	ChannelADigital Output
30	SCLK/DTP	SPI Clock input/Digital test code
31	SDIO/OLM	SPI Data input and output/Output channel mode
32	CSB	SPI Chip selection signal, low enable operation,30 kΩ Internal pull-up
33	PDWN	Digital input,30kΩ Internal Drop Down PDWN high=Switch-off device PDWN low=Equipment operation, normal operation
35	VIN - A	ChannelAAnalog input-
36	VIN + A	ChannelAAnalog input+
37	VIN + B	ChannelBAnalog input+
38	VIN - B	ChannelBAnalog input-
40	RBIAS	Analog current bias, with10 kΩ (1%)Resistance grounding
41	SENSE	Reference voltage mode selection
42	VREF	Reference voltage input/Output
43	VCM	Analog input common mode voltage
44	SYNC	Digital input, frequency divider synchronous input
47	VIN - C	ChannelCAnalog input-
48	VIN + C	ChannelCAnalog input+

8.0 Typical performance test curves (refer to)

Unless otherwise indicated, AVDD = 1.8 V、DRVDD = 1.8 V、VIN = -1.0 dBFS Differential input, $f_s = 125\text{MSPS}$, $T_A = 25^\circ\text{C}$ 1.0 V Internal reference voltage.



9.0 Timing diagram

9.1 Data timing

Unless otherwise indicated, AVDD = 1.8 V、DRVDD = 1.8 V、fs = 125MSPS、VIN = - 1.0 dBFS Differential input, 1.0 V Internal reference voltage.

parameter	Temperature	Minimum	Typical value	Maximum	Units
Clock input parameters					
Input clock rate	Full	20		1000	MHz
Conversion rate	Full	20		125	MHz
aperture					
Aperture delay (tA)	25°C		1		ns
shake	25°C		135		fs rms
Out-of-range recovery time	25°C		1		tcycle
Data output parameters					
Transmission delay tPD			3		ns
FCO Propagation delay tFCO	Full	1.5	2.3	3.1	ns
DCO Propagation delay tCPD	Full		tFCO+(tSAMPLE/16)		ns
DCO To data delay tDATA	Full	(tSAMPLE/16)-300	(tSAMPLE/16)	(tSAMPLE/16)+300	ps
DCO To FCO Delay tRAME	Full	(tSAMPLE/16)-300	(tSAMPLE/16)	(tSAMPLE/16)+300	ps
Channel delay tLD			90		ps
Wakeup time (await the opportune moment)	25°C		250		ns
Wakeup time (Power saving mode)	25°C		375		us
Pipeline delay	Full		16		tcycle

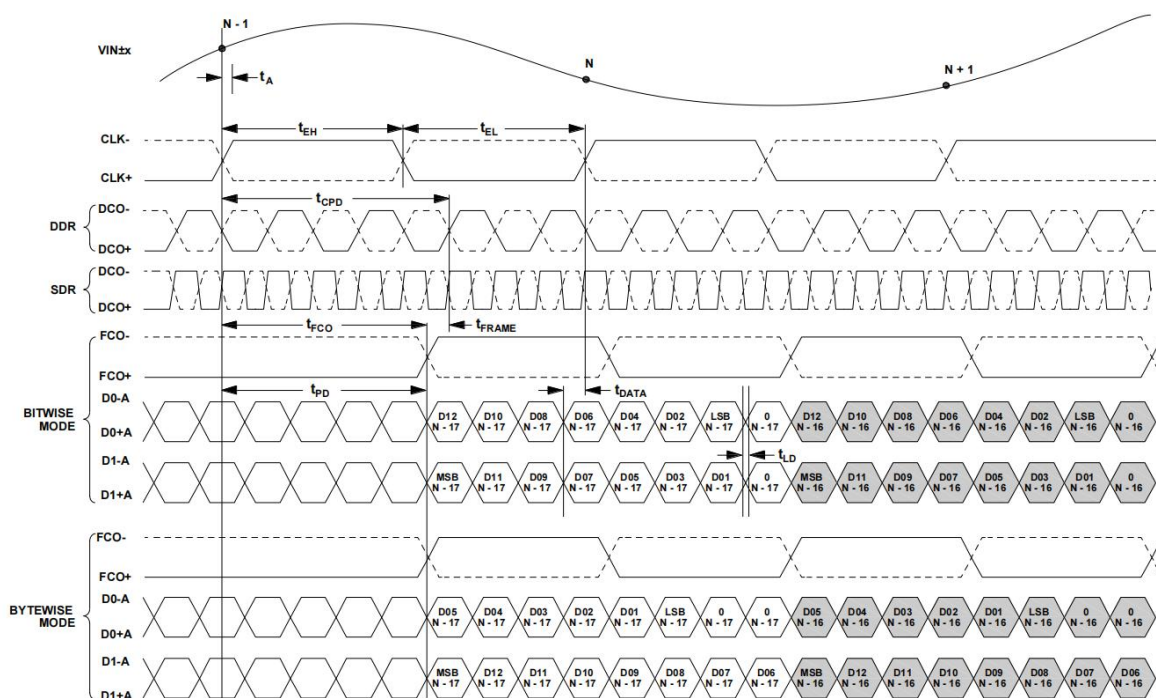


Figure9.1 16-Bit DDR/SDR, Two-Lane, 1xFrame(Default)Working sequence diagram

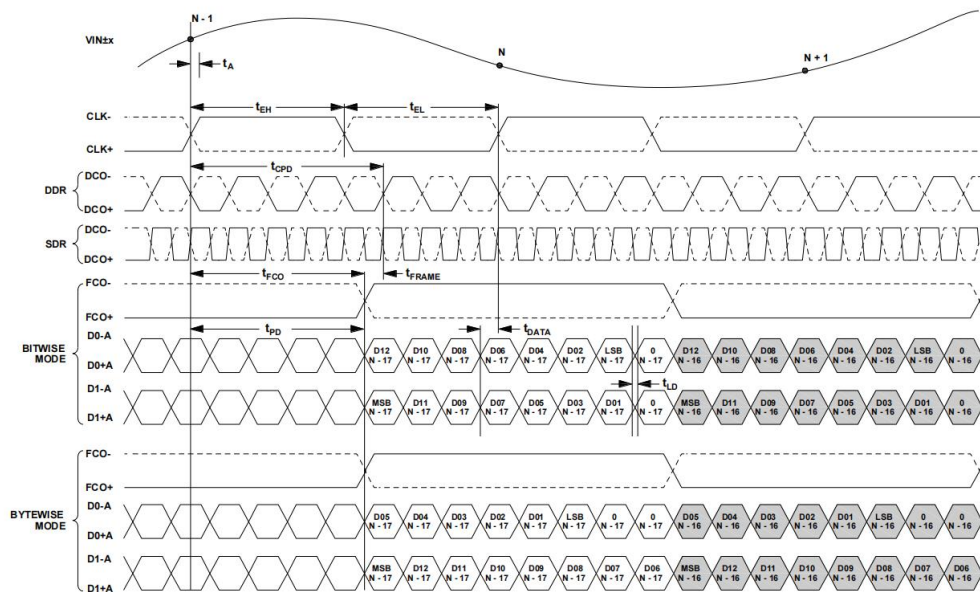


Figure9.2 16-Bit DDR/SDR, Two-Lane, 2xFrame Working sequence diagram

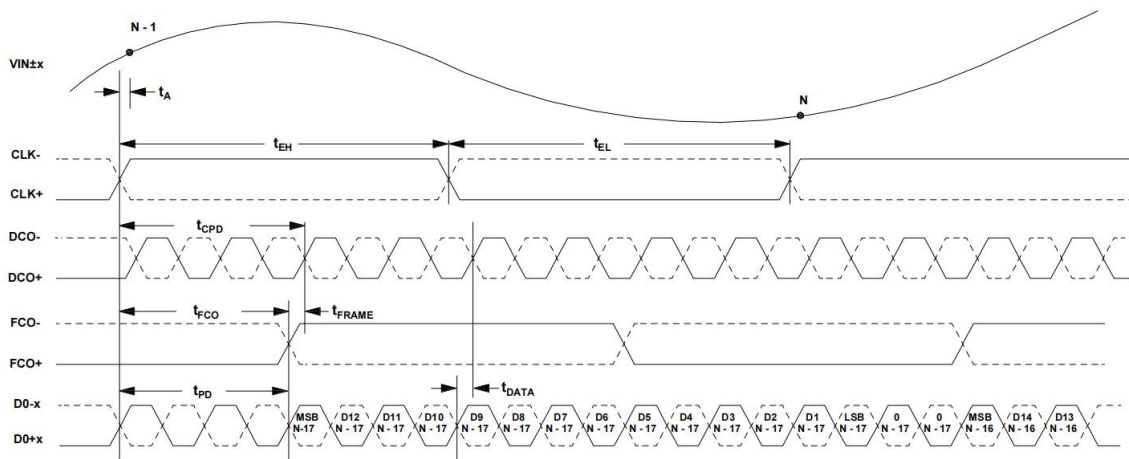


Figure9.3 16-Bit DDR, One-Lane, 1xFrame Working sequence diagram

9.2 SPI Interface timing

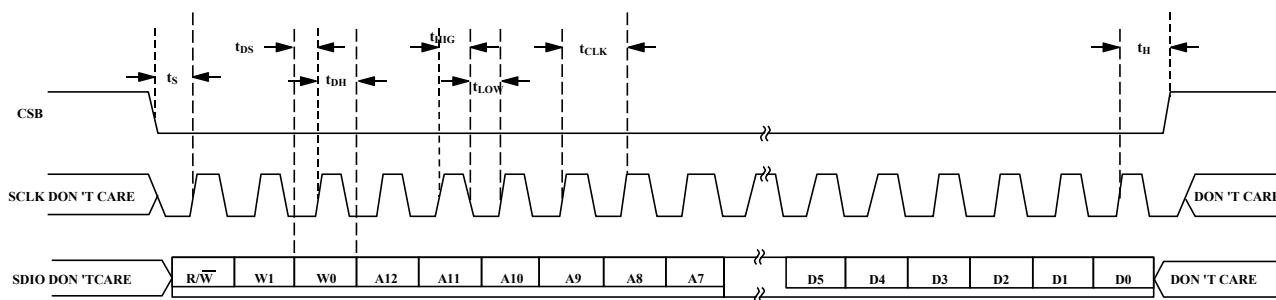


Figure9.4 Serial port interface timing

TABLE9.2 SPI Timing parameters

parameter	condition	Limits
t_{DS}	Data with SCLK Settling time between rising edges	2ns, minimum
t_{DH}	Data with SCLK Hold time between rising edges	2ns, minimum
t_{CLK}	SCLK cycle	40ns, minimum
t_s	CSB With SCLK Establishment time between	2ns, minimum
t_H	CSB With SCLK Hold time between	2ns, minimum
t_{HIG}	SCLK High-level pulse width	10ns, minimum
t_{LOW}	SCLK Low-level pulse width	10ns, minimum

10.0 Working Principle

CW9253-125 It is a multi-stage, pipeline type ADC, each level provides sufficient overlap to correct the upper level Flash Error. The quantized outputs of each stage are combined in one in the digital correction logic, a 14 Bit conversion result. Serializer starts with 14 The bit output format sends this converted data. The pipelined architecture allows the first stage to handle new The sample is entered while the other stages continue to process the previous sample. Sampling takes place on the rising edge of the clock. Except for the last stage, each stage of the pipeline consists of a low-resolution Flash Type ADC a switched capacitor connected thereto DAC And an interstage margin amplifier (Such as multiplicative digital-to-analog converter (MDAC) Composition. Amplification and reconstruction of margin amplifier DAC Output with Flash Type input difference to be supplied to the next stage of the pipeline. In order to help Flash The error is digitally corrected, and the redundancy amount of one bit is set for each stage. The last level consists only of one Flash Type ADC Composition. The output stage module can realize data alignment, error correction, and transmit data to the output buffer. The data is then serialized and aligned with the frame and data clock.

10.1 Analog input network

ADC The best performance of is achieved by differentially driving analog inputs. Using a differential dual-balun configuration to drive CW9253-125, providing excellent performance and Flexible ADC Interface (See figure 10.1). When the input frequency is in the second or higher Nyquist region, the noise performance of most amplifiers cannot meet the requirements to achieve CW9253-125 Genuine SNR Performance, differential transformer coupling is the recommended input configuration (See figure 10.2). Regardless of configuration, shunt capacitors C1 The value of depends on the input frequency and may need to be reduced or removed.

Use VIN- to connect the common mode voltage and VIN + to connect the input signal to the input network mode. This input mode will cause the chip SNR to deteriorate, so it is not recommended to single-ended drive the CW9253-125 input

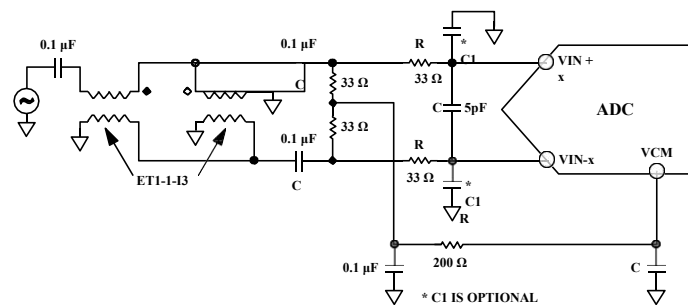


Figure 10.1 Differential dual balun input configuration

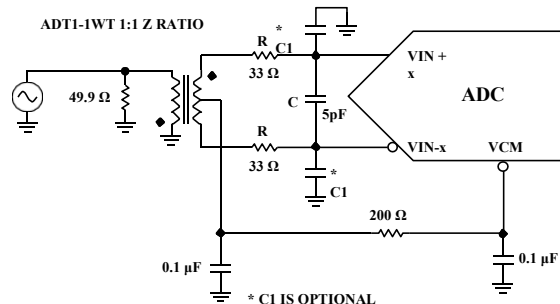


Figure 10.2 Coupling input configuration of differential transformer

10.2 Clock input network

To give full play to the performance of the chip, a differential signal should be used as CW9253-125 Sampling clock input (CLK +/-). The clock signal. The input clock pin has internal bias No external bias is required. It is recommended to sample the RF transformer configuration, as shown in Figure 10.3 Shown in. A back-to-back Schottky diode connected across the transformer may provide input to CW9253-125 Middle The clock signal is limited to about the differential 0.8 V Peak-to-Peak. In this way, the large voltage swing of the clock can be prevented from being fed through to other parts, and the rapid rise and fall of the signal can be preserved This is very important for low jitter performance.

CW9253-125 Has a flexible clock input structure. CMOS、LVDS、LVPECL Or a sine wave signal can be used as its clock input signal. Regardless of which signal is used, clock source jitter must be taken into account (See Jitter Considerations section for description). Figure 10.2 For CW9253-125 Preferred Method of Providing Clock Signals (The clock rate before internal clock division can reach 1GHz). The single-ended signal of a low-jitter clock source can be converted into a differential signal using an RF transformer or RF balun. For 125 MHz To 1 GHz Clock frequency, recommended RF balun configuration; For 20 MHz To 200 MHz Clock frequency, it is recommended to use RF transformer configuration. Cross-connected to transformer/Back-to-back Schottky Two on Balun Secondary Winding The pole tube can input to CW9253-125 The clock signal in is limited to approximately differential 0.8 V Peak-to-Peak. In this way, it is possible to prevent the large voltage swing of the clock from feeding through to CW9253-125 Of In other parts, the fast rise and fall time of the signal can also be preserved, which is very important to achieve low jitter performance. However, when the frequency is higher than 500 MHz Time, the two poles

The tube capacitance makes a difference. Care must be taken to select the appropriate signal limiting diode.

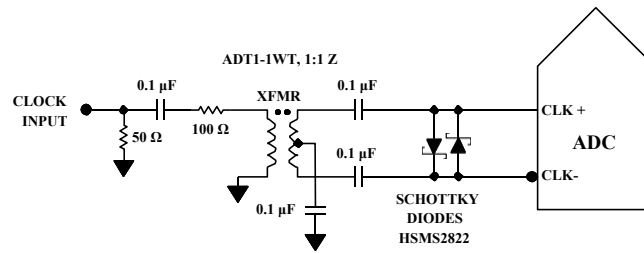


Figure 10.3 Clock input configuration

10.3 Baseline configuration method

The CW9253-125 has a built-in stable, accurate voltage reference. The VREF can be configured with an internal 1.0 V reference voltage, an externally applied 1.0 V to 1.3 V reference voltage, or an external resistor applied to the internal reference voltage to produce a reference voltage according to the user's choice. For a summary of the various reference modes, see the Internal Reference Connection section and the External Reference Configuration section. The VREF pin shall be bypassed to ground by an external parallel combination of a low ESR 0.1 μF ceramic capacitor and a low ESR 1.0 μF capacitor

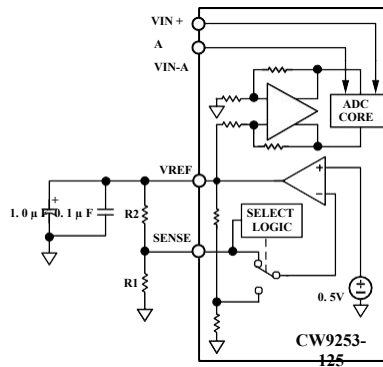


Figure 10.4 Programmable internal reference configuration

TABLE 10.1 Reference Voltage Configuration Summary

Selected mode	SENSE Voltage	Corresponding V_{REF} (V)	Corresponding scoring range (V_{pp})
Fixed internal reference voltage	AVDD To 0.2	1.0, internal	2
Programmable internal voltage reference	External resistor configuration	$0.5 \times (1 + R2/R1)$	$2 \times V_{REF}$
Fixed external reference voltage	AGND to 0.2	1.0 To 1.3, by external V_{REF} Pin offers	2.0~2.6

10.4 Digital output format

The CW9253-125 output driver is an LVDS interface, and the timing is shown in Figure 9.1. The output driver should be able to provide sufficient output current to drive various logic circuits, and the driving force can be adjusted by registers. However, large drive currents may lead to glitch pulses in the power supply signal, affecting the performance of the converter. Therefore, external buffers or latches may be required in applications that require an ADC to drive large capacitive loads or large fan-outs. The format of the output data defaults to binary complement. See Table 10.2 for an example of the output encoding format. To change the output data format to offset binary code, please refer to the "Memory Mapping" section.

In DDR mode, data from each ADC is serialized and provided through different channels. The data rate of each serial stream is equal to 14 bits times the sampling clock rate, and the maximum value is 500 Mbps per channel $[(16 \text{ bits} \times 125 \text{ MSPS}) / (2 \times 2) = 500 \text{ Mbps/channel}]$. The typical minimum conversion rate is 20 MSPS. For more information on using this feature, see the "Memory Mapping" section.

To help capture data from the CW9253-125, the device provides two output clocks. The DCO is used to timing the output data. In the default operation mode, it is equal to 4 times the sampling clock (CLK) rate. Data is output from CW9253-125 one by one and must be captured on the rising and falling edges of the DCO; DCO supports double data rate (DDR) capture.

The FCO is used to indicate the start of a new output byte, and in 1 × frame mode, it is equal to the sampling clock rate. See the Timing Diagram section for more information

Input (V)	condition	Offset binary mode	Binary complement pattern
VIN + - VIN-	$< -V_{REF} - 0.5 \text{ LSB}$	0000 0000 0000 0000	1000 0000 0000 0000
VIN + - VIN-	$= -V_{REF}$	0000 0000 0000 0000	1000 0000 0000 0000
VIN + - VIN-	$= 0$	1000 0000 0000 0000	0000 0000 0000 0000
VIN + - VIN-	$= +V_{REF} - 1 \text{ LSB}$	1111 1111 1111 1100	0111 1111 1111 1111
VIN + - VIN-	$> +V_{REF} - 0.5 \text{ LSB}$	1111 1111 1111 1100	0111 1111 1111 1111

When using SPI, the DCO phase can be adjusted in 60 ° increments with respect to one data period (30 ° with respect to one DCO period). This enables users to optimize system timing margins as needed. As shown in Figure 9.1, the default DCO ± output data edge timing is 180 ° relative to a data cycle (90 ° relative to a DCO cycle).

In the default mode, as shown in Figure 9.1, the MSB is first in the data output serial stream. This can be reversed by using SPI so that the LSB is in the first place in the data output serial stream.

10.5 Output Test Mode

The Output Test options are described in Table 10.3 and are controlled by the Output Test Mode bit at address 0x0D. When the output test mode is enabled, the analog part of the ADC is disconnected from the digital back-end block and the test mode runs through the output format block. Some test modes are constrained by the output format, others are not. The PN generator in the PN sequence test can be reset by setting bit 4 or bit 5 of register 0x0D. These tests can be performed on an analog signal (which is ignored if present) but requires a clock signal.

Table 10.3 Flexible output test modes

Output measurement Trial mode Bit sequence	Schema Name	Digital output word1	Digital output word2	Accept data format selection	annotation
0	Off (default)	N/A	N/A	N/A	
1	Intermediate level short code	1000 0000 0000 0000(16-bit)	N/A	Yes	Offset binary code
10	Positive full scale	1111 1111 1111 1111(16-bit)	N/A	Yes	Offset binary code
11	Negative full scale	0000 0000 0000 0000(16-bit)	N/A	Yes	Offset binary code
100	Checkerboard form	1010 1010 1010 1010(16-bit)	0101 0101 0101 0101(16-bit)	No	
101	PNCode length sequence	N/A	N/A	Yes	PN23 ITU 0.150 $X^{23} + X^{18} + 1$
110	PNCode short sequence	N/A	N/A	Yes	PN9 ITU 0.150X ⁹ + X ⁵ + 1
111	1/0 Word flip	111 1111 1111 1111(16-bit)	0000 0000 0000 0000(16-bit)	No	
1000	User input	Register 0x19 to Register 0x1A	Register 0x1B to Register 0x1C	No	
1001	1/0 bitFlip	1010 1010 1010 1010(16-bit)	N/A	No	
1010	1 × sync	0000 0001 1111 1111(16-bit)	N/A	No	
1011	1Bit high level	1000 0000 0000 0000(16-bit)	N/A	No	Test code associated with external pins
1100	Mixing frequency	1010 0001 1001 1100(16-bit)	N/A	No	

TABLE10.4 PN Sequence

Sequence	Initial value	The first three output samples (MSB Prioritize) Binary complement
PNCode short sequence	0x7F83	0x5F17, 0xB209, 0xCED1
PNCode length sequence	0x7FFF	0x7E00, 0x807C, 0x801F

For information on how to change these additional digital output timing characteristics via SPI, see the Register List.

10.6 CSB Pin

For applications that do not require SPI mode operation, the CSB pin should be connected to the AVDD. By setting CSB to high, all SCLK and SDIO information will be ignored.

When the CSB pin is connected to the AVDD, the CW9253-125, DCS is turned on by default and remains on until the device enters SPI mode and is controlled by SPI.

10.7 RBIAS Pin

The CW9253-125 requires the user to place a 10 kΩ resistor between the RBIAS pin and ground. The series resistor is used to set the main reference current of the ADC core, and the resistor tolerance is at least 1%.

10.8 Serial Port Interface (SPI)

The CW9253-125 Serial Port Interface (SPI) allows users to configure the corresponding function registers within the ADC to meet the needs of specific functions and operations. Through the serial port, the address space can be accessed and read and written to the address space. The SPI of this ADC consists of three parts: the SCLK pin, the SDIO pin and the CSB pin. The SCLK (serial clock) pin is used to synchronize the read and write data of the ADC; The SDIO (Serial Data Input/Output) dual function pin allows data to be sent to or read from internal registers; The CSB (Chip Select Signal) pin is a low-level active control pin, which enables or disables read and write cycles.

The timing requirements are shown in Figure 9.4

11.0 Application Information

11.1 Power and Grounding Recommendations

It is recommended to use two separate 1.8 V power supplies to power the CW9253-125: one for the analog side AVDD and one for the digital output side DRVDD. For AVDD and DRVDD, multiple different decoupling capacitors should be used to support high and low frequencies. Decoupling capacitors should be placed close to the PCB entry point and close to the device pins, with as short trace length as possible.

The CW9253-125 requires only one PCB ground plane. Reasonable decoupling and clever separation of PCB analog, digital and clock modules makes it easy to achieve optimal performance.

11.2 Recommendations for exposed pad heat sinks

For optimal electrical and thermal performance, the exposed pads at the bottom of the ADC must be connected to the analog ground AGND. The exposed continuous copper plane on the PCB should match the exposed pads of the CW9253-125. There should be multiple vias on the copper plane in order to obtain the lowest possible thermal resistance path for heat dissipation through the bottom of the PCB. These vias should be filled or plugged to prevent tin infiltration of the vias and affecting the connection performance. In order to maximize the coverage and connection between the ADC and the PCB, a silk screen layer should be covered on the PCB to divide the continuous plane on the PCB into multiple equal parts. In this way, multiple connection points can be provided between the ADC and the PCB during the reflow soldering process. A continuous, undivided plane can only guarantee a connection point between the ADC and the PCB.

11.3 VCM

The VCM pin should be decoupled to ground through a 0.1 uF capacitor.

11.4 Voltage reference decoupling

The VREF pin should be decoupled to ground by an external parallel connection of a low ESR 0.1 uF ceramic capacitor and a low ESR 1.0 uF capacitor.

11.5 SPI Port

The SPI port should be disabled when the converter is required to give full play to its full dynamic performance. Typically the SCLK signal, CSB signal, and SDIO signal are asynchronous with the ADC clock, so the noise in these signals can degrade converter performance. If other devices use the on-board SPI bus, a buffer may need to be connected between this bus and the CW9253-125 to prevent these signals from changing at the input of the converter during the critical sampling period.

12.0 Register List

Register mapping is broadly divided into the following parts: chip configuration registers, device index registers, and transfer registers, and globalADC Function registers including settings,Control and test functions.

ADDR (HEX)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default (HEX)	annotation
Chip configuration register											
0x00	SPIPort configuration	0 = SDO Effective	LSB Prioritize	Soft ComplexBit	1 = 16-bit address	1 = 16-bit address	Soft ComplexBit	LSB Prioritize	0 = SDO Effective	0x18	The ADC default is 16-bit mode
0x01	ChipID									0xB5	ChipID, read-only
0x02	Chip grade	disable	Chip speed rating			disable	disable	disable	disable		Chip speed rating, read-only
Device index and transfer register											
0x04	Device Index	disable	disable								
0x05	Device Index	disable	disable	Clock channel DCO	Clock channel FCO	DatacomTao D	Data Channel C	Data channels B	Data ChannelA	0x3F	Determining which channel on the chip receives the next write command; The default value is all channels on chip
0xFF	transmission	disable	disable	disable	disable	disable	disable	disable	cover	0x00	Set sampling rate override
overall situationADCFunction register											
0x08	Power consumption mode (FullBureau)	disable	disable	External power down pin function 0=FinishDrop it allElectricity1=To wait Machine	disable	disable	disable	Power consumption mode 00=Work normally 01=Complete power loss 10=await the opportune moment 11=restoration		0x00	Determine the general operating mode of the chipFormula
0x09	Clock (global)	disable	disable	disable	disable	disable	disable	disable	Duty cycle stabilization 0=Open 1=Close	0x01	Duty cycle stabilizer (Difference from imports)
0x0B	Clock division (FullBureau)	disable	disable	disable	disable	disable	Clock division ratio[2:0] 000=1 Frequency division 001=2 Frequency division 010=3 Frequency division 011=4 Frequency division 100=5 Frequency division 101=6 Frequency division 110=7 Frequency division 111=8 Frequency division			0x00	
0x0D	Test Mode (local)	User input test mode		restoration PN Long sequence Column	restoration PN Short sequence Column	Output test mode[3:0] (Local) 0000=Closed (Default) 0001=Intermediate level short sequence 0010=Positive full scale 0011=Negative full scale 0100=Alternating checkerboard form 0101 = PN 23 Sequence 0110 = PN 9 Sequence 0111=1/0 Word inversion 1000=User Defined 1001=1 ×synchronization 1011=1 Bit high level 1100=Mixing frequency (Specific output format reference table11.3)				0x00	Test mode enabled, not subject to modeInfluence of pseudo-input signal
0x10	Offset adjustment (BureauDepartment)	8 Bit device offset adjustment, bit[7:0] Offset adjustment toLSB, from+127 To-128 (Binary complement)								0x00	Device offset adjustment
0x14	Output Mode	disable	0 = LVDS S-ANSI 1 = LVDS S-IEEE LVDS Output swing	disable	disable	disable	Output Reverse direction ()	disable	Output Format 0 = Offset Binary 1 = binary complement (global)	0x01	Configure output and data formats
0x15	Output adjustment	disable	Output driver termination 00=without 01 = 200 Ω 10 = 100 Ω 11 = 100 Ω		disable	disable	disable		Output drive 0=1 × Drive 1=2 × Drive	0x00	LVDS Output configuration
0x16	Output phase	disable	Input clock phase adjustment [6: 4] (input whose value is phase delay Number of clock cycles)			Output clock phase adjustment[3:0] (0000 To1011)				0x03	On devices that utilize global clock division, it is decided which phase of the divider output is used to provide the output clock. Internal latches are not affected.

0x18	VREF Adjustment	disable	disable	disable	disable	disable	VREF Adjustment scheme[2:0] 000 = 1.0 Vpp (1.3 Vpp) 001 = 1.14 Vpp (1.48 Vpp) 010 = 1.33 Vpp (1.73 Vpp) 011 = 1.6 Vpp (2.08 Vpp) 100 = 2.0 Vpp (2.6 Vpp)			0x04	Adjust the interiorVREF Value
0x19	User _ PATT 1 _ LSB(overall situation)										User-defined tests1LSB
0x1A	User _ PATT 1 _ MSB(overall situation)										User-defined tests1MSB
0x1B	User _ PATT 2 _ LSB(overall situation)										User-defined tests2LSB
0x1C	User _ PATT 2 _ MSB(overall situation)										User-defined tests2MSB
0x21	Serial output datacontrol(overall situation)	LVDS Output LSB Excellent First	SDR/DDR Single/Dual-channel, one-by-oneBit/Byte by byte[6:4] 000=SDR Dual-channel, bit-wise 001=SDR Dual-channel, byte-by-byte 010=DDR Dual-channel, bit-wise 011=DDR Dual-channel, verbatimSection 100=DDR Single channel, verbatim			disable	Select 2X Frame	Serial output bits 00=16 Bit		0x30	Serial Stream Control. Defaults to MSB Priority,
0x22	Serial channel status (local)	disable	disable	disable	disable	disable	disable	Channel output reset	Channel power down	0x00	Used to turn off each of the convertersPart
0x100	Sampling rate coverage	disable	Operate to makeca n	0	0	disable	Sampling rate 000 = 20 MSPS 001 = 40MSPS 010 = 50 MSPS 011 = 65MSPS 100 = 80 MSPS 101 = 105 MSPS 110 = 125 MSPS			0x00	Sampling rate coverage
0x109	synchronization	disable	disable	disable	disable	disable	disable	Synchr onous pulse with next onlysynchronization	Enable synchronization	0x00	

13.0 Encapsulation information

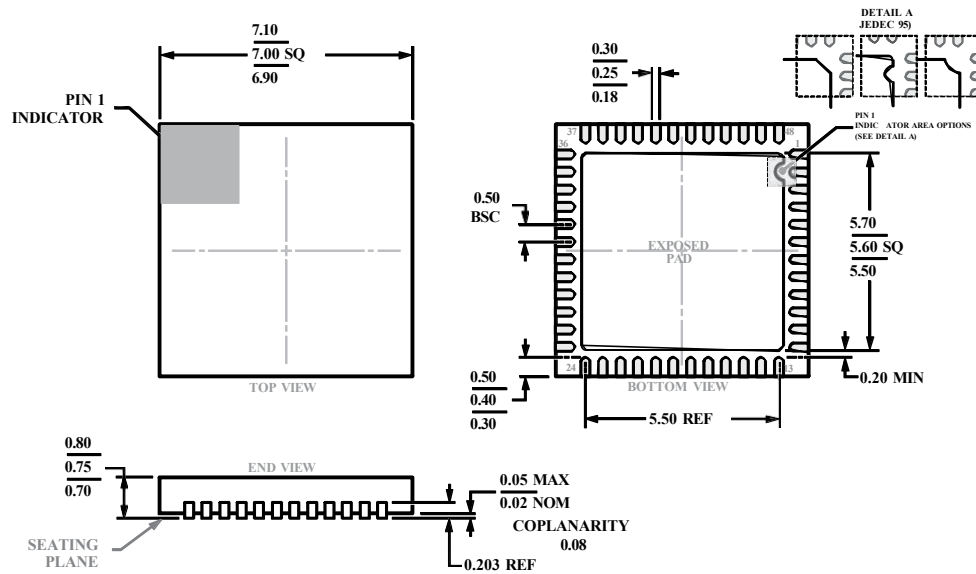


Figure13.1 CW9253-125 Package profile

13.1 Order information

Order model	Operating temperature	Encapsulation form	Execution Standard (Quality grade)
CW9253-125E	-55°C~+125°C	QFN-48	Military warm level